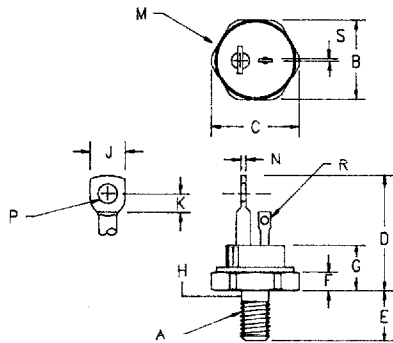


Silicon Controlled Rectifier Series 050



Dim.	Inches		Millimeter		Notes
	Minimum	Maximum	Minimum	Maximum	
A	---	---	---	---	1
B	.677	.685	17.20	17.40	
C	---	.770	---	19.56	
D	1.200	1.250	30.48	31.75	
E	.427	.447	10.84	11.35	
F	.115	.155	2.92	3.94	
G	---	.515	---	13.08	
H	.220	.249	5.58	6.32	2
J	.200	.300	5.08	7.62	
K	.120	---	3.05	---	
M	---	.667	---	16.94	Dia.
N	.065	.085	1.65	2.15	
P	.145	.155	3.68	3.93	Dia.
R	.055	.065	1.40	1.65	Dia.
S	.025	.030	.64	.76	

Note 1: 1/4-28 UNF-3A
Note 2: Full thread within 2 1/2 threads

TO-208AC (TO-65)

Microsemi Catalog Number	Forward & Reverse Repetitive Blocking	Reverse Transient Blocking
05002GOF	200	300
05004GOF	400	500
05006GOF	600	700
05008GOF	800	900
05010GOF	1000	1100
05012GOF	1200	1300

To specify dv/dt other than 200V/usec., contact factory.

- dv/dt-200 V/usec
- 1200 Amperes surge current
- Economical for medium power applications
- Compact TO-208AC package

Electrical Characteristics

Max. RMS on-state current	$I_T(\text{RMS})$ 80 Amps	$T_C = 94^\circ\text{C}$
Max. average on-state cur.	$I_T(\text{AV})$ 50 Amps	$T_C = 94^\circ\text{C}$
Max. peak on-state voltage	V_{TM} 2.3 Volts	$I_{TM} = 500 \text{ A(peak)}$
Max. holding current	I_H 200 mA	$T_C = 94^\circ\text{C}$ 60Hz
Max. peak one cycle surge current	I_{TSM} 1200 Amps	$t = 8.3 \text{ ms}$
Max. I^2t capability for fusing	I^2t 6000A ² S	

Thermal and Mechanical Characteristics

Operating junction temp range	T_J	-40°C to 125°C
Storage temperature range	T_{STC}	-40°C to 150°C
Maximum thermal resistance	$R_{\theta JC}$	0.35°C/W Junction to case
Typical thermal resistance	$R_{\theta CS}$	0.20°C/W Case to sink
Max mounting torque		30 inch pounds maximum
Weight		0.56 ounces (16 grams) typical

Microsemi Corp.
Colorado

050

T_J = 25°C unless otherwise indicated

Switching			
Critical rate of rise of on-state current (note 1)	dI/dt	200A/usec.	T _J = 125°C
Typical delay time (note 1)	t _d	3.0 usec.	T _J = 125°C
Typical circuit commuted turn-off time (note 2)	t _q	100 usec.	T _J = 125°C
Note 1: I _{TM} = 50A, V _D = V _{DRM} , G _T = 12V open circuit, 20 ohm-0.1 usec. rise time Note 2: I _{TM} = 50A, dI/dt = 5A/usec., V _R during turn-off interval = 50V min., reapplied dv/dt = 20V/usec., linear to rated V _{DRM} , V _{GT} = 0V			

Triggering			
Max. gate voltage to trigger	V _{GT}	3.0V	T _J = 125°C
Typical gate voltage to trigger	V _{GT}	1.0V	
Max. nontriggering gate voltage	V _{GD}	0.25V	
Max. gate current to trigger	I _{GT}	100mA	t _p = 10 usec.
Typical gate current to trigger	I _{GT}	48mA	
Max. peak gate power	P _{GM}	10W	
Average gate power	P _{G(AV)}	1.0W	
Max. peak gate current	I _{GM}	3.0A	
Max. peak gate voltage (forward)	V _{GM}	20V	
Max. peak gate voltage (reverse)	V _{GM}	10V	

Blocking			
Max. leakage current	I _{DRM}	6mA	T _J = 125°C & V _{DRM}
Max. reverse leakage	I _{RRM}	6mA	T _J = 125°C & V _{RRM}
Critical rate of rise of off-state voltage	dv/dt	200V/usec.	T _J = 125°C



Figure 1
Typical Forward On-State Characteristics

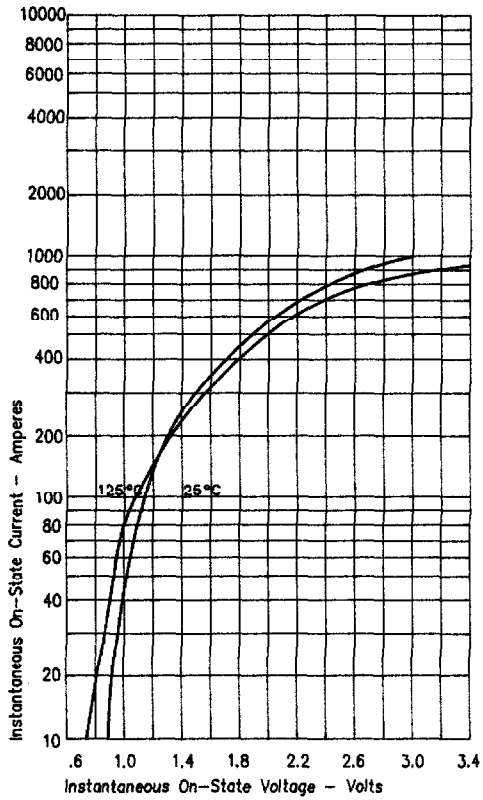


Figure 3
Maximum Power Dissipation

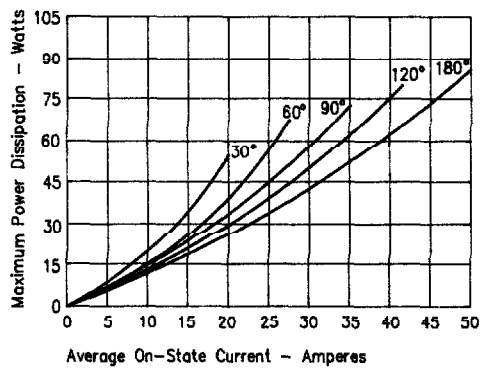


Figure 4
Transient Thermal Impedance

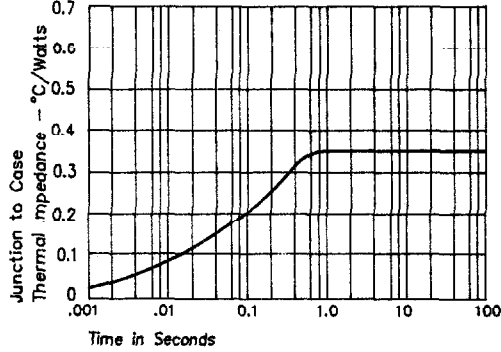


Figure 2
Forward Current Derating

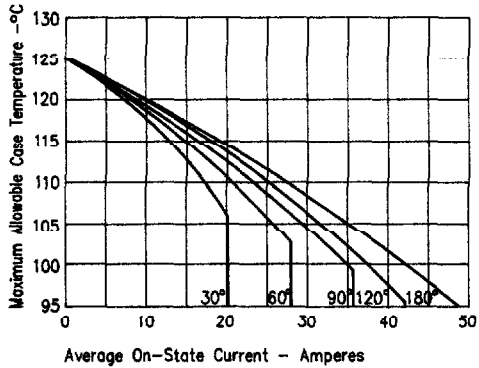


Figure 5
Maximum Nonrepetitive Surge Current

